

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jong Han KIM</td> <td>10/18/2011</td> </tr> <tr> <td>Hyun Chul JEONG</td> <td>10/18/2011</td> </tr> </tbody> </table>		Name	Execution Date	Jong Han KIM	10/18/2011	Hyun Chul JEONG	10/18/2011
Name	Execution Date						
Jong Han KIM	10/18/2011						
Hyun Chul JEONG	10/18/2011						
RECEIVING PARTY DATA							
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.						
Street Address:	314 Maetan 3-dong, Yeongtong-gu, Suwon,						
City:	Gyeonggi-do						
State/Country:	REPUBLIC OF KOREA						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13333220</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13333220		
Property Type	Number						
Application Number:	13333220						
CORRESPONDENCE DATA							
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
Correspondent Name:	MCDERMOTT WILL & EMERY LLP						
Address Line 1:	600 13TH STREET, N.W.						
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20005-3096						
ATTORNEY DOCKET NUMBER:	090104-0071						
NAME OF SUBMITTER:	Stephen A. Becker/ksa						
Total Attachments: 2 source=0901040071assigntransmittal#page1.tif source=0901040071assign#page1.tif							

CH \$40.00 13333220

RECORDATION FORM COVER SHEET

Docket No.: 090104-0071

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)
Jong Han KIM, Hyun Chul JEONG

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**
 Internal Address:
 Address: **314 Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea**

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **October 18, 2011**

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License

4. Application or patent number(s):
 A. Patent Application No(s).

This document is being filed together with a new application.
 B. Patent No(s).

5. Name and address to whom correspondence concerning document should be mailed:

Name: **MCDERMOTT WILL & EMERY LLP**
 Internal Address:
 Street Address: **600 13th Street, N.W.**
 City: **Washington, State: DC Zip: 20005-3096 D.C.**
 Phone Number: **202.756.8000**
 Fax Number: **202.756.8087**
 Email Address: **mweipdocket@mwe.com**


6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers _____
 Expiration Date _____
 b. Deposit Account Number 500417
 Authorized User Name _____

9. Signature.
Stephen A. Becker 26,527  **December 21, 2011**

Name and Registration No. of Person Signing _____ Signature _____ Date _____

Total number of pages including cover sheet, attachments and documents: **2**

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) KIM, Jong Han (5) _____
- (2) JEONG, Hyun Chul (6) _____
- (3) _____ (7) _____
- (4) _____ (8) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto
SAMSUNG ELECTRO-MECHANICS CO., LTD.

314 Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled **CERAMIC ELECTRONIC COMPONENT AND METHOD OF MANUFACTURING THE SAME**

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

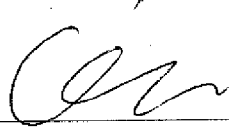
(b) for which an application for United States Letters Patent was executed on _____, and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention herchy transferred.

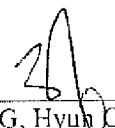
SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

1) 

2011. 10. 18

2) 

2011. 10. 18